

TYN30Y-800T

Rev.01 - 09 September 2019

Product data sheet

1. General description

Planar passivated Silicon Controlled Rectifier (SCR) in a IITO220 plastic package intended for use in applications requiring very high inrush current capability, high thermal cycling performance and high junction temperature capability ($T_{j(max)} = 150$ °C).

2. Features and benefits

- AC power control
- High blocking voltage capability
- · High thermal cycling performance
- · Planar passivated for voltage ruggedness and reliability
- · High immunity to false turn-on by dV/dt
- Internally insulated package
- Internally isolated mounting base
- High junction operating temperature capability (T_{j(max)} = 150 °C)
- Package meets UL94V0 flammability requirement
- Package is RoHS compliant
- IEC 61000-4-4 fast transient

3. Applications

- Capacitive Discharge Ignition (CDI)
- Crowbar protection
- Inrush protection
- Motor control
- Voltage regulation

4. Quick reference data

Table 4. Outals as fearing a state

Symbol	Parameter	Conditions	Values	Unit
V_{DRM}	repetitive peak off-state voltage		800	V
I _{T(RMS)}	RMS on-state current	half sine wave; T _{mb} ≤ 114 °C; <u>Fig. 1; Fig. 2; Fig. 3</u>	30	A
I _{TSM}	non-repetitive peak on- state current	half sine wave; $T_{j(init)}$ = 25 °C; t_p = 10 ms; Fig 4; Fig 5	350	A
		half sine wave; $T_{j(init)}$ = 25 °C; t_p = 8.3 ms	385	А
T _j	junction temperature		150	°C

Symbol Parameter Conditions Min Max Unit Тур **Static characteristics** V_D = 12 V; I_T = 0.1 A; T_i = 25 °C; <u>Fig. 7</u> 6 15 mΑ gate trigger current I_{GT} _ holding current V_D = 12 V; T_i = 25 °C; <u>Fig. 9</u> 60 mΑ $I_{\rm H}$ _ - V_{T} on-state voltage I_T = 60 A; T_i = 25 °C; <u>Fig. 10</u> 1.3 1.5 V _ **Dynamic characteristics** dV_D/dt V_{DM} = 402 V; T_i = 150 °C; exponential rate of rise of off-state 1000 V/µs -waveform; gate open circuit voltage

5. Pinning information

Table 2. P	inning infor	mation		
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	К	cathode	\square	
2	А	anode		А Д К G
3	G	gate		sym037
mb	n.c.	mounting base; isolated		

6. Ordering information

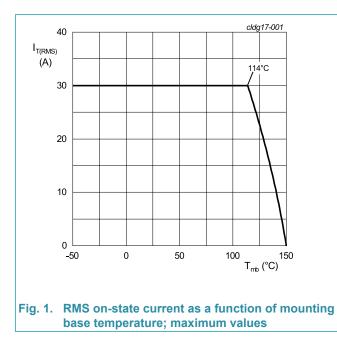
Table 3. Ordering information							
Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date	
TYN30Y-800T	IITO220	TYN30Y-800TQ	Tube	50	IITO220E	15-Dec-2017	

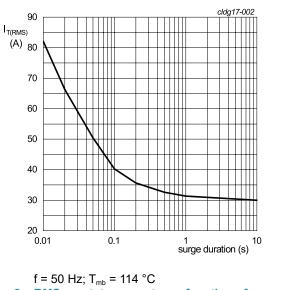
7. Limiting values

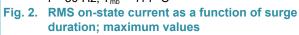
Table 4. Limiting values

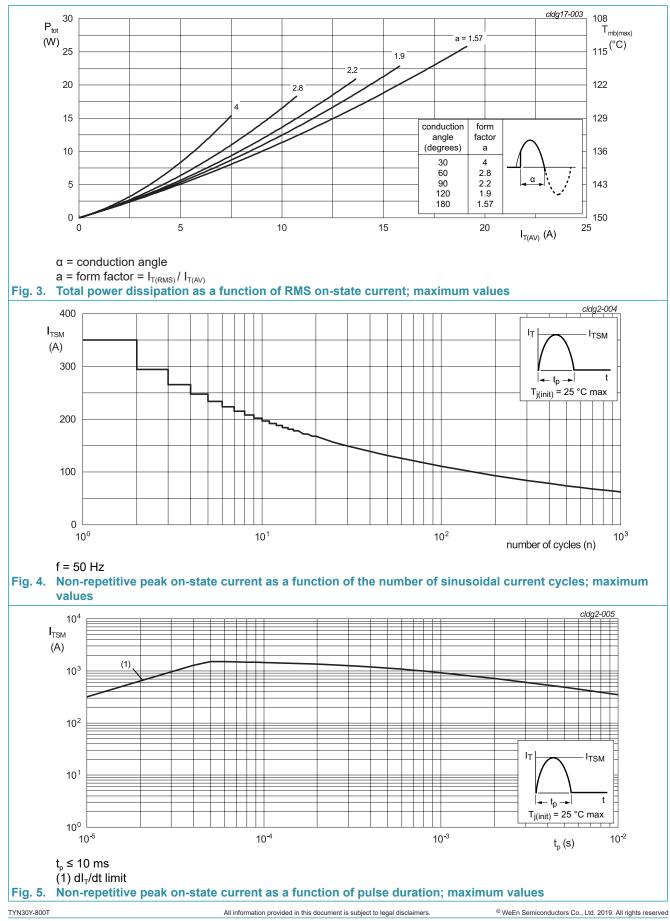
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{DRM}	repetitive peak off-state voltage		800	V
V_{RRM}	repetitive peak reverse voltage		800	V
I _{T(AV)}	average on-state current	half sine wave; T _{mb} ≤ 114 °C;	19	А
$\mathbf{I}_{\mathrm{T(RMS)}}$	RMS on-state current	half sine wave; T _{mb} ≤ 114 °C; <u>Fig. 1; Fig. 2; Fig. 3</u>	30	A
I _{TSM}	non-repetitive peak on- state current	half sine wave; $T_{j(init)} = 25 \text{ °C}$; $t_p = 10 \text{ ms}$; Fig 4; Fig 5	350	A
		half sine wave; $T_{j(init)}$ = 25 °C; t_p = 8.3 ms	385	А
l ² t	l ² t for fusing	t _p = 10 ms; sine-wave pulse	612.5	A ² s
dl _⊤ /dt	rate of rise of on-state current	I _G = 30 mA	100	A/µs
I _{GM}	peak gate current		5	А
V_{GM}	peak gate voltage		5	V
P _{GM}	peak gate power		20	W
P _{G(AV)}	average gate power	over any 20 ms period	0.5	W
T _{stg}	storage temperature		-40 to 150	°C
Tj	junction temperature		150	°C



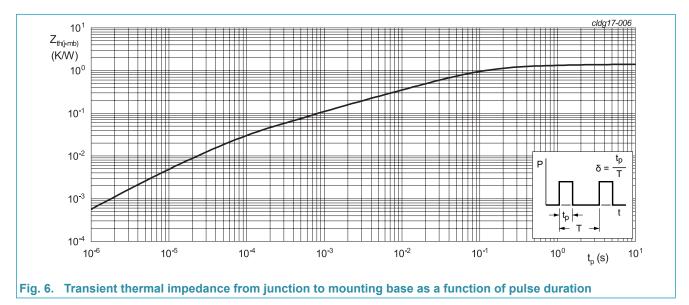






8. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<u>Fig 6</u>	-	-	1.4	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	-	60	-	K/W



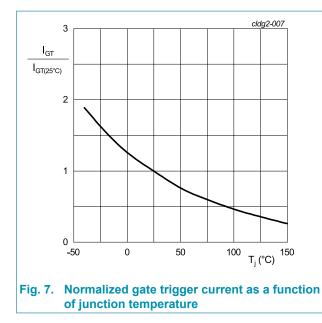
9. Isolation characteristics

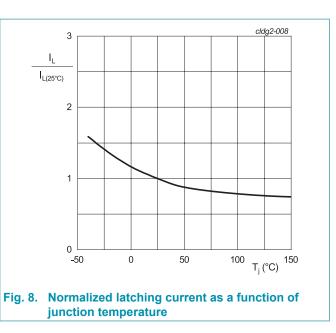
Table 6. Isolation characteristics

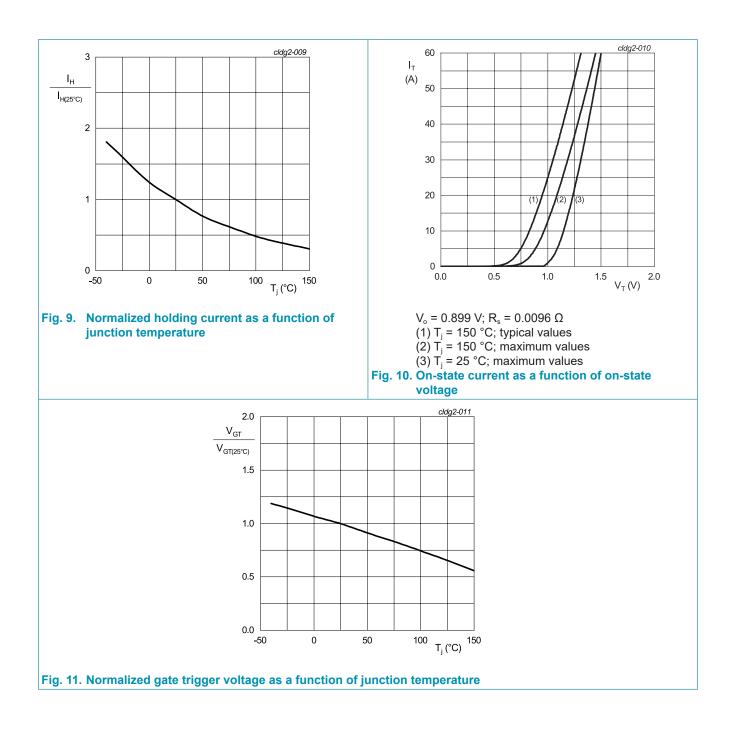
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{isol(RMS)}	RMS isolation voltage	50 Hz \leq f \leq 60 Hz; RH \leq 65 %; from all pins to external heatsink; sinusoidal waveform; clean and dust free	-	-	2500	V
Cisol	isolation capacitance	from cathode to external heatsink	-	10	-	pF

10. Characteristics

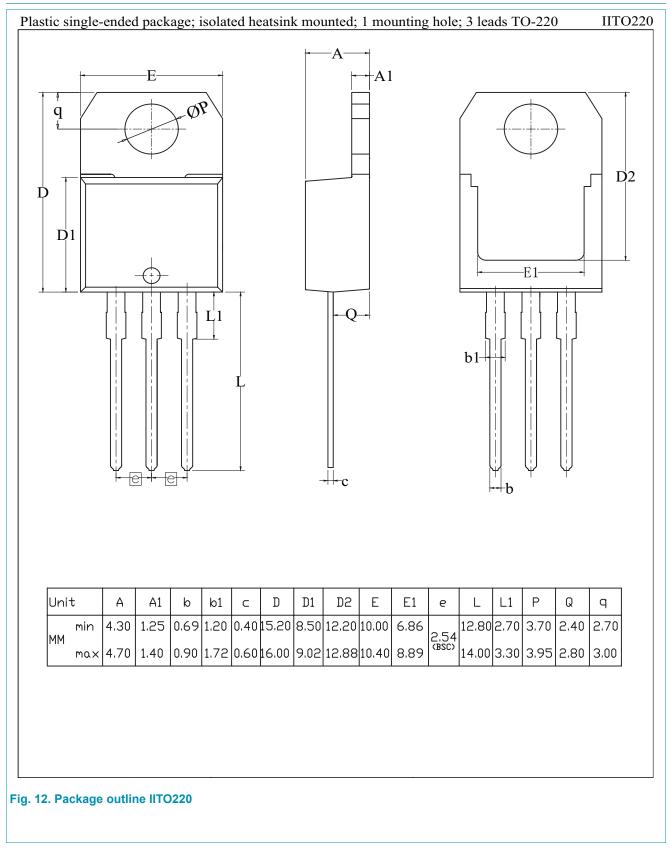
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics	· · ·				
I _{GT}	gate trigger current	V _D = 12 V; I _T = 0.1 A; T _j = 25 °C; <u>Fig. 7</u>	6	-	15	mA
I _L	latching current	V _D = 12 V; I _G = 0.1 A; T _j = 25 °C; <u>Fig. 8</u>	-	-	80	mA
I _H	holding current	V _D = 12 V; T _j = 25 °C; <u>Fig. 9</u>	-	-	60	mA
V _T	on-state voltage	I _T = 60 A; T _j = 25 °C; <u>Fig. 10</u>	-	1.3	1.5	V
V_{GT}	gate trigger voltage	V _D = 12 V; I _T = 0.1 A;T _j = 25 °C; <u>Fig. 11</u>	-	0.6	1	V
		V _D = 400 V; I _T = 0.1 A;T _j = 125 °C	0.25	0.4	-	V
I _D	off-state current	V _D = 800 V; T _j = 150 °C	-	-	1	mA
I _R	reverse current	V _R = 800 V; T _j = 150 °C	-	-	1	mA
Dynamic	characteristics	· · · ·	I	,		
$dV_{\rm D}/dt$	rate of rise of off-state voltage	V_{DM} = 402 V; T _j = 150 °C; exponential waveform; gate open circuit	1000	-	-	V/µs
		$V_{DM} = 536 \text{ V}; \text{ T}_{j} = 150 \text{ °C}; (V_{DM} = 67\% \text{ of } V_{DRM}); exponential waveform; gate open circuit$	500	-	-	V/µs
t _{gt}	gate-controlled turn-on time	$I_{TM} = 30 \text{ A}; V_D = 800 \text{ V}; I_G = 100 \text{ mA};$ $dI_G/dt = 5 \text{ A}/\mu\text{s}; T_j = 25 \text{ °C}$	-	2	-	μs
t _q	commutated turn-off time	$V_{DM} = 536 \text{ V}; \text{ T}_{j} = 150 \text{ °C}; \text{ I}_{TM} = 30 \text{ A};$ $V_{R} = 25 \text{ V}; \text{ dI}_{T}/\text{dt} = 30 \text{ A}/\mu\text{s}; \text{ dV}_{D}/\text{dt} = 50 \text{ V}/\mu\text{s}$	-	70	-	μs







11. Package outline



12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

- [2] The term 'short data sheet' is explained in section "Definitions".
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